

Title (en)  
FLEX-RIGID PRINTED CIRCUIT BY BONDING

Title (de)  
FLEXIBEL-STARRE LEITERPLATTE DURCH BONDIERUNG

Title (fr)  
CIRCUIT IMPRIME FLEX-RIGIDE PAR COLLAGE

Publication  
**EP 1803338 A1 20070704 (FR)**

Application  
**EP 05775280 A 20050602**

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Abstract (en)  
[origin: WO2006000694A1] The invention concerns the field of printed circuits. The invention concerns a method for connecting a rigid circuit to a flexible printed circuit, characterized in that it consists, successively, in bonding the end of the flexible printed circuit on the end of the rigid circuit, so as to ensure that the electric contact pads of both circuits are superimposed back-to-back, piercing said assembly at said electric contact pads, and electrically connecting said punch-throughs by silk-screening deposition of a conductive paste.

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